

REMARKS/ARGUMENTS

The present Amendment is responsive to the non-final Office Action mailed August 20, 2007 in the above-identified application.

Claims 1-9 are the claims currently pending in the present application.

Claim 1 is amended to clarify a feature recited thereby. This Amendment is fully supported by Applicant's disclosure, see, for example, specification, page 5, lines 31-34.

Objection to the Abstract

The Abstract of the Disclosure is objected to on the ground that it includes legal terms and redundant phrases. A replacement Abstract is filed herewith.

Rejection of Claims 1-9 under 35 U.S.C. § 103

Claims 1-9 are rejected under 35 U.S.C. § 103 as being obvious from Nishiura et al., U.S. Patent No. 6,112,974 in view of Ano, U.S. Patent No. 6,815,836. Reconsideration of this rejection is respectfully requested.

Claim 1 requires a method of bonding wire between first and second bonding points with a bonding tool, comprising moving the bonding tool from the first position towards the first bonding point and applying a pressing force on the first bond with the wire without forming a second bond with a wire.

Nishiura discloses a wire bonding method in which after forming the first bond the capillary is moved to a position located at an upward inclination in the direction of the second bonding point, then moved to a position at an upward inclination in the opposite direction from the second bonding point, then lowered to the second bonding point (Nishiura, Abstract).

The Office Action at page 3 alleges that Nishiura discloses the above-cited feature of claim 1. However, as made clear in the summary of the operations at Nishiura, column 4, lines 54-65, the capillary travels repeatedly at an upward inclination until it is lowered to bond the wire to the second

bonding point (the second bonding point is spaced from the first bonding point). Thus first, Nishiura does not disclose or suggest moving the bonding tool towards the first bonding point, as required by claim 1. Further, Nishiura does not disclose or suggest after this step, applying a pressing force on the first bond with the wire but without forming a bond, as further required by claim 1. Accordingly, Nishiura does not disclose or suggest the features of claim 1.

The shortcomings of Ano have been discussed in previously filed Amendments (for example, in the Amendment filed August 3, 2006), and the Examiner does not now allege that Ano discloses or suggest the above-cited features of claim 1. Ano does not disclose or suggest applying a pressing force on the first bond but without forming a second bond of the wire, as further required by claim 1. Therefore, even taken together in combination, Nishiura and Ano do not disclose or suggest the above-cited features of claim 1.

Claims 2-9 depend from claim 1 and are therefore patentably distinguishable over the cited art for at least the same reasons.

In view of the foregoing discussion, withdrawal of the objection and the rejection and allowance of the application are requested.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 14, 2007

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Name of applicant, assignee or
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Signature

November 14, 2007

Date of Signature

RCF:GB:bar

Respectfully submitted,



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